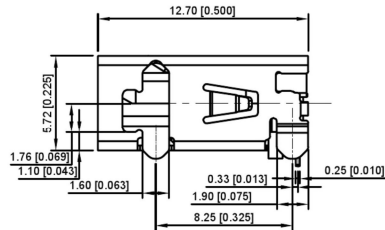
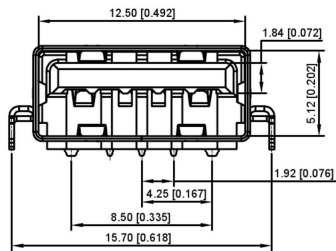
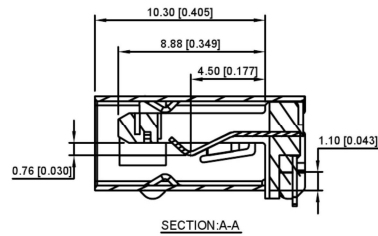
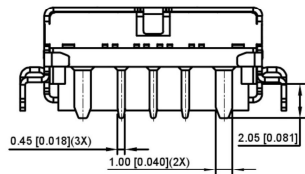


RECOMMENDED PCB LAYOUT(TOP VIEW)  
THICKNESS 1.0±0.10MM;DEFAULT TOLERANCE:±0.05

U224-05XN-3GRA035

- G: GREEN
- B: BLACK
- BL: BLUE
- 1: Au 1U"
- 5: Au 15U"
- 6: Au 30U"
- 1: PBT
- 2: PA6T
- 3: PA9T
- 4: LCP



NOTE:

1. MATERIAL SPECIFICATION:
  1. HOUSING: PA10T, UL94V-0
  2. CONTACTS: COPPER ALLOY (C7025)
  3. FRONT SHELL: STAINLESS STEEL (SUS201)
2. PLATING SPECIFICATION:
  - 2-1. TERMINAL:
    - Ni 50u" MIN. UNDER PLATED OVER ALL.
    - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT (GOLD PLATING THICKNESS FOLLOW THE P/N PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N)
  - 2-2. FRONT SHELL:
    - Ni 30u" MIN. UNDER PLATED OVER ALL.
3. MECHANICAL PERFORMANCE
  - 3-1. INSERTION FORCE: 3.5Kgf MAX
  - 3-2. REMOVAL FORCE: 1.02kgf MIN
  - 3-3. DURABILITY: 1500 CYCLES.
4. ELECTRICAL PERFORMANCE,
  - 4-1. CURRENT RATING:
    - VBUS & GND PINS: 5A MAX.
    - OTHER PINS: 0.25A MAX.
  - 4-2. LLCR:
    - VBUS & GND PINS: 30mΩ/PIN MAX.
    - ALL OTHER PINS: 50mΩ/PIN MAX.
    - LLCR MAX. CHANGE OF ALL PINS: 10mΩ
  - 4-3. INSULATION RESISTANCE: 100MΩ MIN
  - 4-4. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
  - OPERATING TEMPERATURE: -25°C ~ +85°C
6. IR REFLOW:
  - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

				ANGLAR	±5°	DSND		SCALE: N/A	MODEL TYPE: USB 2.0					
				L ≤ 4	±0.2	DWN		VIEW:	PART NO.:					
				4 < L ≤ 16	±0.3	CHKD		UNIT: mm/in	DWG NO.:					
				16 < L ≤ 63	±0.4	APPD		SIZE: A4	U224-05XN-3GRA035					
				L > 63	±0.5				WEIGHT	SHEET	REVISION			
DESCRIPTION				DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES							
REVISIONS							KE SI DA ELECTRONIC TECHNOLOGY CO., LTD							
WWW.BODONGKAIGUAN.NET				WWW.CKJACK.COM				WWW.KSDKG.COM						
										1/1	A0			

